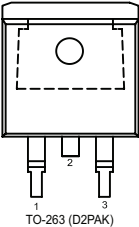
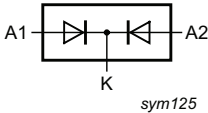


5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode [1]		
3	A2	anode 2		
mb	K	mounting base; cathode		

[1] it is not possible to make a connection to pin 2 of the TO263 package

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYV32EB-200	TO263	BYV32EB-200,118	Reel	800	TO263N	26-Sep-2016

7. Marking

Table 4. Marking codes

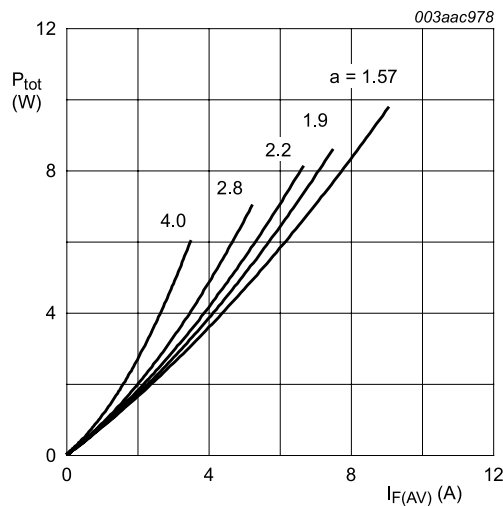
Type number	Marking codes
BYV32EB-200	BYV32EB-200

8. Limiting values

Table 5. Limiting values

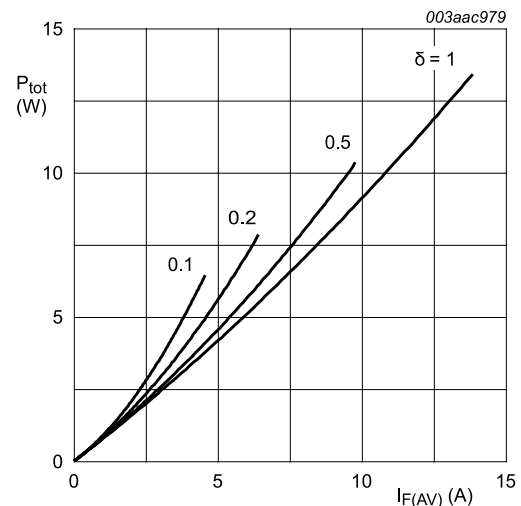
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		200	V
V_{RWM}	crest working reverse voltage		200	V
V_R	reverse voltage	DC	200	V
$I_{O(AV)}$	average output current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 115\text{ }^{\circ}\text{C}$; both diodes conducting; Fig 1; Fig 2	20	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 115\text{ }^{\circ}\text{C}$; per diode	20	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; per diode	125	A
		$t_p = 8.3\text{ ms}$; sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; per diode	137	A
I_{RRM}	repetitive peak reverse current	$\delta = 0.001$; $t_p = 2\text{ }\mu\text{s}$; per diode	0.2	A
I_{RSM}	non-repetitive peak reverse current	$t_p = 100\text{ }\mu\text{s}$; per diode	0.2	A
T_{stg}	storage temperature		-40 to 150	$^{\circ}\text{C}$
T_j	junction temperature		150	$^{\circ}\text{C}$
V_{ESD}	electrostatic discharge voltage	HBM; all pins; $C = 250\text{ pF}$; $R = 1.5\text{ k}\Omega$	8	kV



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

Fig. 1. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

Fig. 2. Forward power dissipation as a function of average forward current; square wave; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; both diodes conducting		-	-	1.6	K/W
		with heatsink compound; per diode; Fig 3		-	-	2.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient			-	60	-	K/W

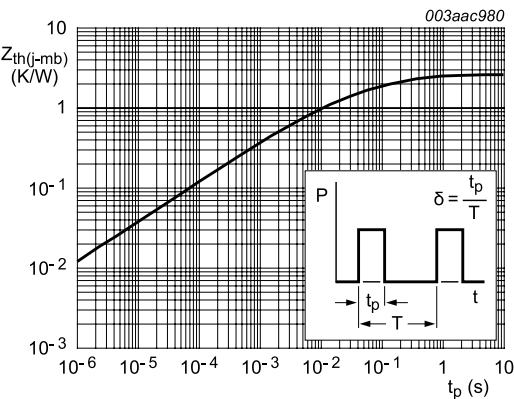
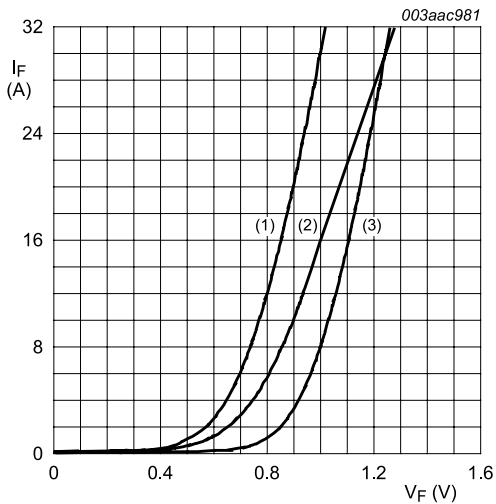


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 8 A; T _J = 150 °C; Fig. 4		-	0.72	0.85	V
		I _F = 20 A; T _J = 25 °C		-	1	1.15	V
I _R	reverse current	V _R = 200 V; T _J = 25 °C		-	6	30	μA
		V _R = 200 V; T _J = 100 °C		-	0.2	0.6	mA
Dynamic characteristics							
Q _r	recovered charge	I _F = 2 A; V _R = 30 V; dI _F /dt = 20 A/μs; T _J = 25 °C		-	8	12.5	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _J = 25 °C; ramp recovery; Fig. 5		-	20	25	ns
		I _F = 0.5 A to I _R = 1 A; T _J = 25 °C; measured at I _R = 0.25 A; step recovery; Fig. 6		-	10	20	ns
V _{FR}	forward recovery voltage	I _F = 1 A; dI _F /dt = 10 A/μs; T _J = 25 °C; Fig. 7		-	-	1	V



(1) $T_J = 150^\circ\text{C}$; typical values
(2) $T_J = 150^\circ\text{C}$; maximum values
(3) $T_J = 25^\circ\text{C}$; maximum values

Fig. 4. Forward current as a function of forward voltage

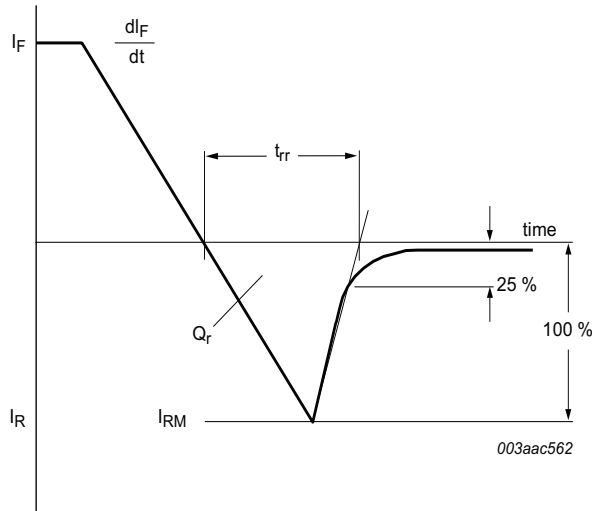


Fig. 5. Reverse recovery definitions; ramp recovery

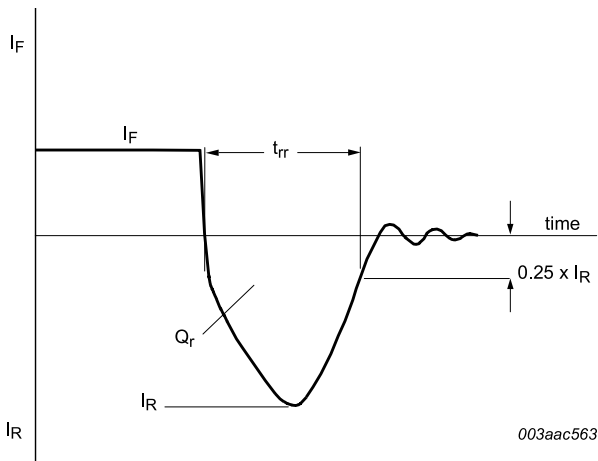


Fig. 6. Reverse recovery definitions; step recovery

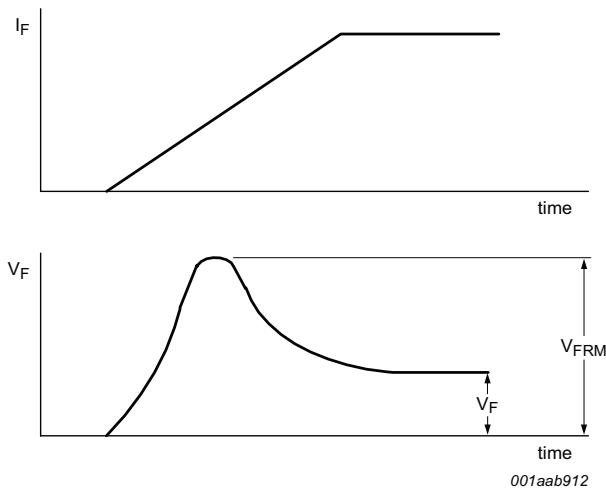
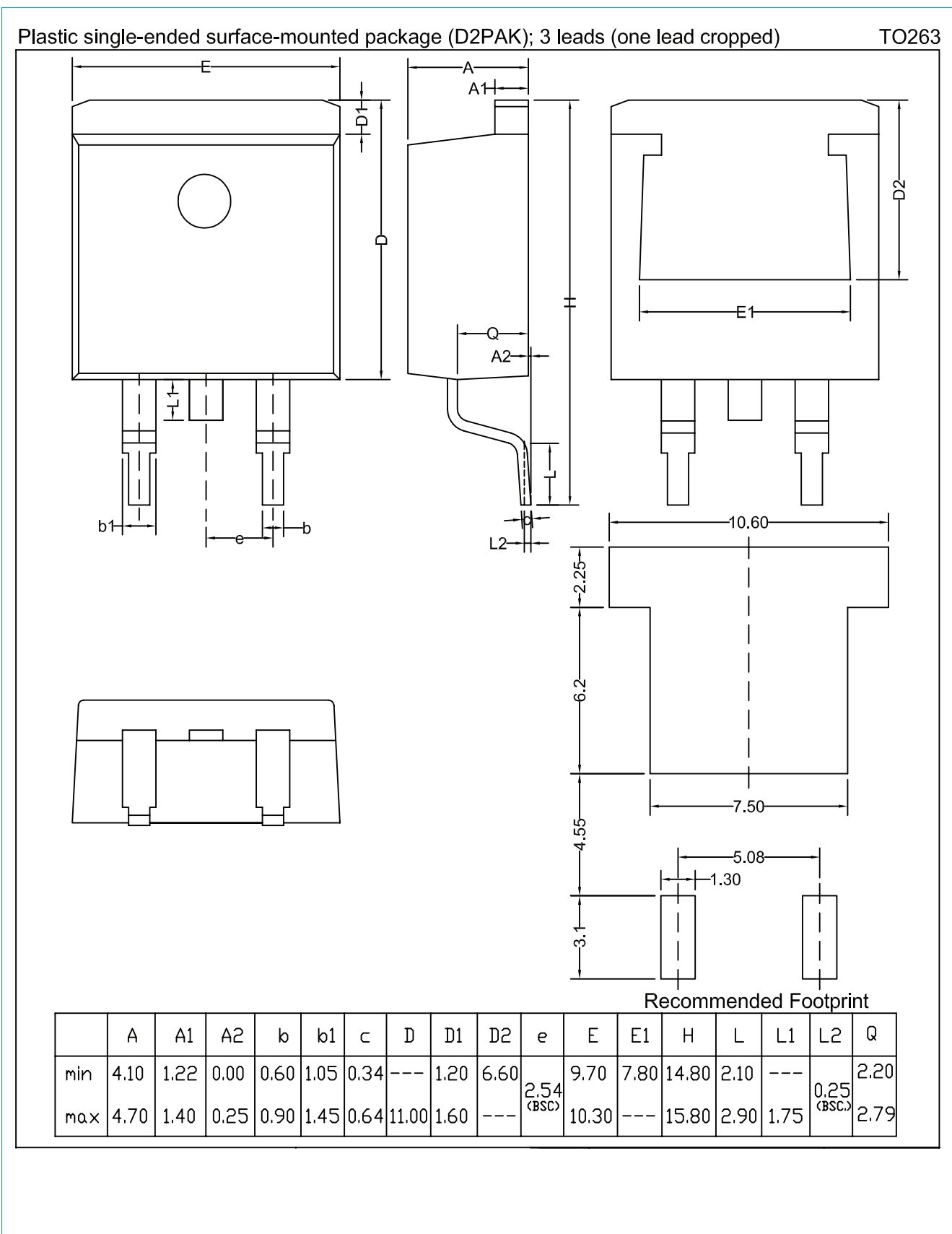


Fig. 7. Forward recovery definitions

11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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